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**Understanding Embedded - CPLDs (Complex Programmable Logic Devices)** 

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### **Applications of Embedded - CPLDs**

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128stc100-15f

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 2. MAX	7000S Device I	Features -				
Feature	EPM7032S	EPM7064S	EPM7128S	EPM7160S	EPM7192S	EPM7256S
Usable gates	600	1,250	2,500	3,200	3,750	5,000
Macrocells	32	64	128	160	192	256
Logic array blocks	2	4	8	10	12	16
Maximum user I/O pins	36	68	100	104	124	164
t <sub>PD</sub> (ns)	5	5	6	6	7.5	7.5
t <sub>SU</sub> (ns)	2.9	2.9	3.4	3.4	4.1	3.9
t <sub>FSU</sub> (ns)	2.5	2.5	2.5	2.5	3	3
t <sub>CO1</sub> (ns)	3.2	3.2	4	3.9	4.7	4.7
f <sub>CNT</sub> (MHz)	175.4	175.4	147.1	149.3	125.0	128.2

### ...and More Features

- Open-drain output option in MAX 7000S devices
- Programmable macrocell flipflops with individual clear, preset, clock, and clock enable controls
- Programmable power-saving mode for a reduction of over 50% in each macrocell
- Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
- 44 to 208 pins available in plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and 1.0-mm thin quad flat pack (TQFP) packages
- Programmable security bit for protection of proprietary designs
- 3.3-V or 5.0-V operation
  - MultiVolt<sup>TM</sup> I/O interface operation, allowing devices to interface with 3.3-V or 5.0-V devices (MultiVolt I/O operation is not available in 44-pin packages)
  - Pin compatible with low-voltage MAX 7000A and MAX 7000B devices
- Enhanced features available in MAX 7000E and MAX 7000S devices
  - Six pin- or logic-driven output enable signals
  - Two global clock signals with optional inversion
  - Enhanced interconnect resources for improved routability
  - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
  - Programmable output slew-rate control
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
  - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
  - The BitBlaster<sup>TM</sup> serial download cable, ByteBlasterMV<sup>TM</sup> parallel port download cable, and MasterBlaster<sup>TM</sup> serial/universal serial bus (USB) download cable program MAX 7000S devices

# General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Device					Speed	l Grade				
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20
EPM7032		<b>✓</b>	<b>✓</b>		<b>✓</b>		<b>✓</b>	<b>✓</b>	<b>✓</b>	
EPM7032S	<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>					
EPM7064		<b>✓</b>	<b>✓</b>		~		<b>✓</b>	<b>✓</b>		
EPM7064S	<b>✓</b>	<b>✓</b>	<b>✓</b>		~					
EPM7096			<b>✓</b>		~		<b>✓</b>	<b>✓</b>		
EPM7128E			<b>✓</b>	<b>✓</b>	~		<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7128S		<b>✓</b>	<b>✓</b>		~			<b>✓</b>		
EPM7160E				<b>✓</b>	<b>✓</b>		<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7160S		<b>✓</b>	<b>✓</b>		~			<b>✓</b>		
EPM7192E						<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7192S			<b>✓</b>		<b>✓</b>			<b>✓</b>		
EPM7256E						<b>✓</b>	<b>✓</b>	<b>✓</b>		<b>✓</b>
EPM7256S			<b>✓</b>		<b>✓</b>			<b>✓</b>		

Figure 2. MAX 7000E & MAX 7000S Device Block Diagram

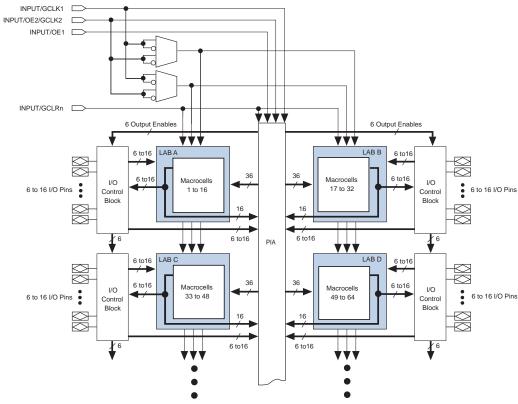


Figure 2 shows the architecture of MAX 7000E and MAX 7000S devices.

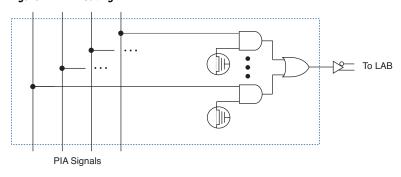
**Logic Array Blocks** 

The MAX 7000 device architecture is based on the linking of high-performance, flexible, logic array modules called logic array blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the programmable interconnect array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

### Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

#### I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V<sub>CC</sub>. Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

### **Programming Sequence**

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- Enter ISP. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- Program. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- Verify. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. Exit ISP. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

### **Programming Times**

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

### Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where:  $t_{PROG}$  = Programming time  $t_{PPULSE}$  = Sum of the fixed times to erase, program, and

verify the EEPROM cells

 $Cycle_{PTCK}$  = Number of TCK cycles to program a device

= TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where:  $t_{VER}$  = Verify time

 $t_{VPULSE}$  = Sum of the fixed times to verify the EEPROM cells

 $Cycle_{VTCK}$  = Number of TCK cycles to verify a device

### Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo Bit<sup>TM</sup> option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder ( $t_{LPA}$ ) for the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ , and  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters.

### Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

### MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V  $V_{\rm CCINT}$  level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When  $V_{\rm CCIO}$  is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with  $V_{\rm CCIO}$  levels lower than 4.75 V incur a nominally greater timing delay of  $t_{\rm OD2}$  instead of  $t_{\rm OD1}$ .

### Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When  $V_{\rm CCIO}$  is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When  $V_{\rm CCIO}$  is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

#### Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

### Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the *Programming Hardware Manufacturers*.

Symbol	Parameter	Conditions	Speed	Grade -6	Speed (	Grade -7	Unit
			Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.4		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.4		0.5	ns
t <sub>FIN</sub>	Fast input delay	(2)		0.8		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.5		4.0	ns
$t_{PEXP}$	Parallel expander delay			0.8		0.8	ns
$t_{LAD}$	Logic array delay			2.0		3.0	ns
t <sub>LAC</sub>	Logic control array delay			2.0		3.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)				2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		2.0		2.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		2.5		2.5	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		7.0		7.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		4.0		4.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		4.5		4.5	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
$t_{SU}$	Register setup time		3.0		3.0		ns
$t_H$	Register hold time		1.5		2.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	2.5		3.0		ns
$t_{FH}$	Register hold time of fast input	(2)	0.5		0.5		ns
$t_{RD}$	Register delay			0.8		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			0.8		1.0	ns
t <sub>IC</sub>	Array clock delay			2.5		3.0	ns
t <sub>EN</sub>	Register enable time			2.0		3.0	ns
t <sub>GLOB</sub>	Global control delay			0.8		1.0	ns
t <sub>PRE</sub>	Register preset time			2.0		2.0	ns
t <sub>CLR</sub>	Register clear time			2.0		2.0	ns
t <sub>PIA</sub>	PIA delay			0.8		1.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		10.0	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			2.0		2.0		3.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t <sub>FIN</sub>	Fast input delay	(2)		2.0		_		4.0	ns
t <sub>SEXP</sub>	Shared expander delay			8.0		10.0		9.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.0		1.0		2.0	ns
t <sub>LAD</sub>	Logic array delay			6.0		6.0		8.0	ns
t <sub>LAC</sub>	Logic control array delay			6.0		6.0		8.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)		3.0		_		4.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		5.0		-		6.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		8.0		-		9.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 3.3 V	C1 = 35 pF (7)		7.0		-		11.0	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		-		14.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t <sub>SU</sub>	Register setup time		4.0		4.0		4.0		ns
t <sub>H</sub>	Register hold time		4.0		4.0		5.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	2.0		-		4.0		ns
$t_{FH}$	Register hold time of fast input	(2)	2.0		-		3.0		ns
t <sub>RD</sub>	Register delay			1.0		1.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.0		1.0		1.0	ns
t <sub>IC</sub>	Array clock delay			6.0		6.0		8.0	ns
t <sub>EN</sub>	Register enable time			6.0		6.0		8.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		1.0		3.0	ns
t <sub>PRE</sub>	Register preset time			4.0		4.0		4.0	ns
t <sub>CLR</sub>	Register clear time			4.0		4.0		4.0	ns
t <sub>PIA</sub>	PIA delay			2.0		2.0		3.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		13.0		15.0		15.0	ns

Table 27. EPM7032S External Timing Parameters (Part 2 of 2)   Note (1)												
Symbol	Parameter	Conditions				Speed	Grade	1			Unit	
			-	-5 -6 -7 -10								
			Min	Max	Min	Max	Min	Max	Min	Max		
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz	
f <sub>MAX</sub>	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz	

Table 2	8. EPM7032\$ Internal Tim	ing Parameter	rs /	Note (1)							
Symbol	Parameter	Conditions				Speed	Grade	)			Unit
			_	5	-	6	-	7	-	10	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
t <sub>FIN</sub>	Fast input delay			2.2		2.1		2.5		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.1		3.8		4.6		5.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.9		1.1		1.4		0.8	ns
$t_{LAD}$	Logic array delay			2.6		3.3		4.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			2.5		3.3		4.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		0.8		1.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t <sub>SU</sub>	Register setup time		0.8		1.0		1.3		2.0		ns
$t_H$	Register hold time		1.7		2.0		2.5		3.0		ns
t <sub>FSU</sub>	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
$t_{RD}$	Register delay			1.2		1.6		1.9		2.0	ns
$t_{COMB}$	Combinatorial delay			0.9		1.1		1.4		2.0	ns
t <sub>IC</sub>	Array clock delay			2.7		3.4		4.2		5.0	ns
t <sub>EN</sub>	Register enable time			2.6		3.3		4.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			1.6		1.4		1.7		1.0	ns
t <sub>PRE</sub>	Register preset time			2.0		2.4		3.0		3.0	ns
t <sub>CLR</sub>	Register clear time			2.0		2.4		3.0		3.0	ns

Table 2	8. EPM7032S Internal Tim	ing Paramete	rs /	lote (1)								
Symbol	Parameter	Conditions				Speed	Grade				Unit	
			-	-5 -6 -7 -10								
			Min	Max	Min	Max	Min	Max	Min	Max		
t <sub>PIA</sub>	PIA delay	(7)		1.1		1.1		1.4		1.0	ns	
$t_{LPA}$	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns	

#### Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 2	Table 29. EPM7064S External Timing Parameters (Part 1 of 2)   Note (1)												
Symbol	Parameter	Conditions	Speed Grade										
			-	5	-	6	-	7	-1	10			
			Min	Max	Min	Max	Min	Max	Min	Max			
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns		
t <sub>SU</sub>	Global clock setup time		2.9		3.6		6.0		7.0		ns		
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns		
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns		
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns		
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns		
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns		
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns		
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		3.0		2.0		ns		
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.0		3.0		ns		

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	6	-	7	-1	10	-1	15	
			Min	Max	Min	Max	Min	Max	Min	Max	-
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.5		0.5		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.5		0.5		2.0	ns
t <sub>FIN</sub>	Fast input delay			2.6		1.0		1.0		2.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.7		4.0		5.0		8.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.1		0.8		0.8		1.0	ns
$t_{LAD}$	Logic array delay			3.0		3.0		5.0		6.0	ns
$t_{LAC}$	Logic control array delay			3.0		3.0		5.0		6.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		2.0		2.0		3.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.4		2.0		1.5		4.0	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		0.9		2.5		2.0		5.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.4		7.0		5.5		8.0	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t <sub>SU</sub>	Register setup time		1.0		3.0		2.0		4.0		ns
t <sub>H</sub>	Register hold time		1.7		2.0		5.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		1.9		3.0		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.5		0.5		1.0		ns
$t_{RD}$	Register delay			1.4		1.0		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.0		1.0		2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			3.1		3.0		5.0		6.0	ns
t <sub>EN</sub>	Register enable time			3.0		3.0		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.0		1.0		1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			2.4		2.0		3.0		4.0	ns
t <sub>CLR</sub>	Register clear time			2.4		2.0		3.0		4.0	ns
$t_{PIA}$	PIA delay	(7)		1.4		1.0		1.0		2.0	ns
$t_{LPA}$	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

Table 33. EPM7160S External Timing Parameters (Part 2 of 2)   Note (1)											
Symbol	Parameter	Conditions				Speed	Grade	1			Unit
			-	6	-	7	-1	0	-1	5	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>ACNT</sub>	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 3	4. EPM7160\$ Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	6	-	7	-1	10	-1	15	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
t <sub>FIN</sub>	Fast input delay			2.6		3.2		1.0		2.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.6		4.3		5.0		8.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.0		1.3		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.8		3.4		5.0		6.0	ns
t <sub>LAC</sub>	Logic control array delay			2.8		3.4		5.0		6.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		0.9		2.0		3.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
t <sub>XZ</sub>	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
t <sub>SU</sub>	Register setup time		1.0		1.2		2.0		4.0		ns
t <sub>H</sub>	Register hold time		1.6		2.0		3.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
$t_{RD}$	Register delay			1.3		1.6		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.0		1.3		2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			2.9		3.5		5.0		6.0	ns
t <sub>EN</sub>	Register enable time			2.8		3.4		5.0		6.0	ns
t <sub>GLOB</sub>	Global control delay			2.0		2.4		1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			2.4		3.0		3.0		4.0	ns

Table 35. EPM7192S External Timing Parameters (Part 2 of 2) Note (1)										
Symbol	Parameter	Conditions	Speed Grade							
			-7		-10		-15		1	
			Min	Max	Min	Max	Min	Max		
t <sub>AH</sub>	Array clock hold time		1.8		3.0		4.0		ns	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns	
t <sub>ACH</sub>	Array clock high time		3.0		4.0		6.0		ns	
t <sub>ACL</sub>	Array clock low time		3.0		4.0		6.0		ns	
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns	
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns	
t <sub>CNT</sub>	Minimum global clock period			8.0		10.0		13.0	ns	
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	125.0		100.0		76.9		MHz	
t <sub>ACNT</sub>	Minimum array clock period			8.0		10.0		13.0	ns	
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	125.0		100.0		76.9		MHz	
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz	

Table 36. EPM7192S Internal Timing Parameters (Part 1 of 2)   Note (1)										
Symbol	Parameter	Conditions	Conditions Speed Grade						Unit	
			-7		-10		-15			
			Min	Max	Min	Max	Min	Max		
t <sub>IN</sub>	Input pad and buffer delay			0.3		0.5		2.0	ns	
t <sub>IO</sub>	I/O input pad and buffer delay			0.3		0.5		2.0	ns	
t <sub>FIN</sub>	Fast input delay			3.2		1.0		2.0	ns	
t <sub>SEXP</sub>	Shared expander delay			4.2		5.0		8.0	ns	
t <sub>PEXP</sub>	Parallel expander delay			1.2		0.8		1.0	ns	
$t_{LAD}$	Logic array delay			3.1		5.0		6.0	ns	
t <sub>LAC</sub>	Logic control array delay			3.1		5.0		6.0	ns	
t <sub>IOE</sub>	Internal output enable delay			0.9		2.0		3.0	ns	
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns	
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns	
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		7.0	ns	
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns	
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns	
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns	
t <sub>XZ</sub>	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns	
t <sub>SU</sub>	Register setup time		1.1		2.0		4.0		ns	

Tables 37 and 38 show the EPM7256S AC operating conditions.

Symbol	Parameter	Conditions	Speed Grade						
			-7 -10				-15		Unit
			Min Max		Min Max		Min Max		
			IVIIII	7.5	IVIIII	10.0	IVIIII	15.0	
t <sub>PD1</sub>	Input to non-registered output I/O input to non-registered output	C1 = 35 pF C1 = 35 pF		7.5		10.0		15.0	ns ns
t <sub>SU</sub>	Global clock setup time		3.9		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t <sub>CH</sub>	Global clock high time		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		0.8		2.0		4.0		ns
t <sub>AH</sub>	Array clock hold time		1.9		3.0		4.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		7.8		10.0		15.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		4.0		6.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		4.0		6.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	3.0		4.0		6.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			7.8		10.0		13.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	128.2		100.0		76.9		MHz
t <sub>ACNT</sub>	Minimum array clock period			7.8		10.0		13.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	128.2		100.0		76.9		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		125.0		100.0		MHz

#### Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $\mathbf{t_{ACL}}$ , and  $\mathbf{t_{CPPW}}$  parameters for macrocells running in the low-power mode.

## Power Consumption

Supply power (P) versus frequency ( $f_{MAX}$  in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The  $P_{IO}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note* 74 (*Evaluating Power for Altera Devices*).

The I<sub>CCINT</sub> value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times tog_{USED}$$

The parameters in this equation are shown below:

 $MC_{TON}$  = Number of macrocells with the Turbo Bit option turned on,

as reported in the MAX+PLUS II Report File (.rpt)

 $MC_{DEV}$  = Number of macrocells in the device

MC<sub>USED</sub> = Total number of macrocells in the design, as reported

in the MAX+PLUS II Report File (.rpt)

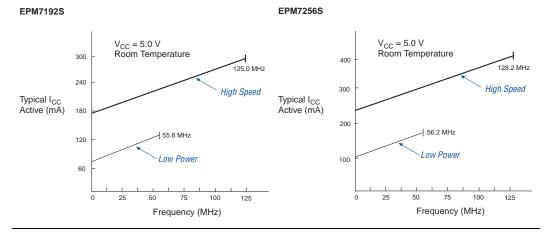
 $f_{MAX}$  = Highest clock frequency to the device

tog<sub>LC</sub> = Average ratio of logic cells toggling at each clock

(typically 0.125)

A, B, C = Constants, shown in Table 39

Figure 15. I<sub>CC</sub> vs. Frequency for MAX 7000S Devices (Part 2 of 2)

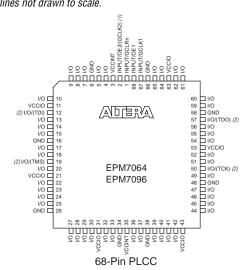


## Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figure 17. 68-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



#### Notes:

- The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.



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I.S. EN ISO 9001